

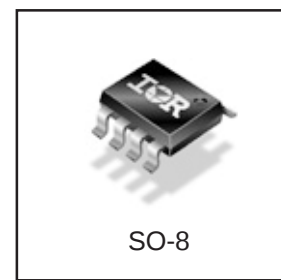
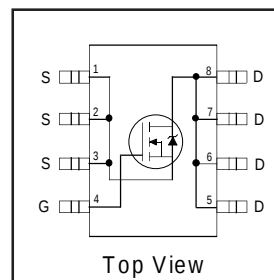
### Applications

- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use
- High Frequency Buck Converters for Computer Processor Power

### Benefits

- Ultra-Low Gate Impedance
- Very Low  $R_{DS(on)}$
- Fully Characterized Avalanche Voltage and Current

| $V_{DSS}$ | $R_{DS(on)}$ max(m $\Omega$ ) | $I_D$ |
|-----------|-------------------------------|-------|
| 20V       | 10@ $V_{GS} = 10V$            | 12A   |



### Absolute Maximum Ratings

| Symbol                     | Parameter                                | Max.         | Units          |
|----------------------------|------------------------------------------|--------------|----------------|
| $V_{DS}$                   | Drain-Source Voltage                     | 20           | V              |
| $V_{GS}$                   | Gate-to-Source Voltage                   | $\pm 20$     | V              |
| $I_D$ @ $T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS}$ @ 10V | 12           | A              |
| $I_D$ @ $T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS}$ @ 10V | 10           |                |
| $I_{DM}$                   | Pulsed Drain Current①                    | 100          |                |
| $P_D$ @ $T_A = 25^\circ C$ | Maximum Power Dissipation③               | 2.5          | W              |
| $P_D$ @ $T_A = 70^\circ C$ | Maximum Power Dissipation③               | 1.6          | W              |
|                            | Linear Derating Factor                   | 0.02         | mW/ $^\circ C$ |
| $T_J, T_{STG}$             | Junction and Storage Temperature Range   | -55 to + 150 | $^\circ C$     |

### Thermal Resistance

| Symbol          | Parameter              | Typ. | Max. | Units        |
|-----------------|------------------------|------|------|--------------|
| $R_{\theta JL}$ | Junction-to-Drain Lead | —    | 20   | $^\circ C/W$ |
| $R_{\theta JA}$ | Junction-to-Ambient ⑤  | —    | 50   |              |

Notes ① through ⑤ are on page 8

# IRF7460

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## Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

|                                 | Parameter                            | Min. | Typ.  | Max. | Units               | Conditions                                           |
|---------------------------------|--------------------------------------|------|-------|------|---------------------|------------------------------------------------------|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 20   | —     | —    | V                   | $V_{GS} = 0V, I_D = 250\mu A$                        |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.089 | —    | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}, I_D = 1mA$           |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | 7.2   | 10   | $m\Omega$           | $V_{GS} = 10V, I_D = 12A$ ④                          |
|                                 |                                      | —    | 10.5  | 14   |                     | $V_{GS} = 4.5V, I_D = 9.6A$ ④                        |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 1.0  | —     | 3.0  | V                   | $V_{DS} = V_{GS}, I_D = 250\mu A$                    |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —     | 20   | $\mu A$             | $V_{DS} = 16V, V_{GS} = 0V$                          |
|                                 |                                      | —    | —     | 100  |                     | $V_{DS} = 16V, V_{GS} = 0V, T_J = 125^\circ\text{C}$ |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —     | 200  | nA                  | $V_{GS} = 16V$                                       |
|                                 | Gate-to-Source Reverse Leakage       | —    | —     | -200 |                     | $V_{GS} = -16V$                                      |

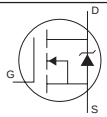
## Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

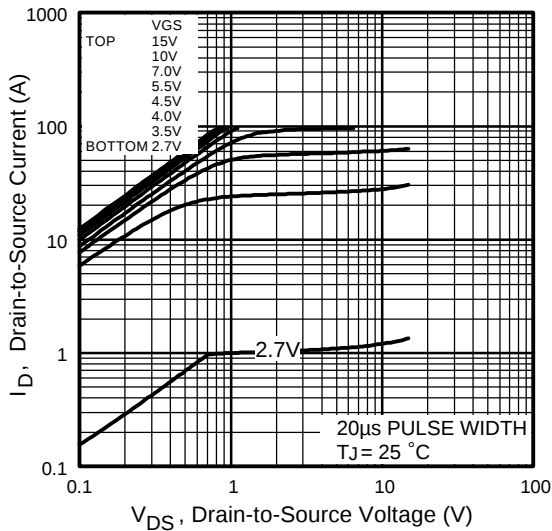
| Symbol       | Parameter                       | Min. | Typ. | Max. | Units | Conditions                  |
|--------------|---------------------------------|------|------|------|-------|-----------------------------|
| $g_{fs}$     | Forward Transconductance        | 26   | —    | —    | S     | $V_{DS} = 16V, I_D = 9.6A$  |
| $Q_g$        | Total Gate Charge               | —    | 19   | —    | nC    | $I_D = 9.6A$                |
| $Q_{gs}$     | Gate-to-Source Charge           | —    | 6.9  | —    |       | $V_{DS} = 10V$              |
| $Q_{gd}$     | Gate-to-Drain ("Miller") Charge | —    | 6.0  | —    |       | $V_{GS} = 4.5V$ , ④         |
| $Q_{oss}$    | Output Gate Charge              | —    | 17   | 26   |       | $V_{GS} = 0V, V_{DS} = 10V$ |
| $t_{d(on)}$  | Turn-On Delay Time              | —    | 11   | —    | ns    | $V_{DD} = 10V$              |
| $t_r$        | Rise Time                       | —    | 6.9  | —    |       | $I_D = 9.6A$                |
| $t_{d(off)}$ | Turn-Off Delay Time             | —    | 12   | —    |       | $R_G = 1.8\Omega$           |
| $t_f$        | Fall Time                       | —    | 4.3  | —    |       | $V_{GS} = 4.5V$ ④           |
| $C_{iss}$    | Input Capacitance               | —    | 2050 | —    | pF    | $V_{GS} = 0V$               |
| $C_{oss}$    | Output Capacitance              | —    | 1060 | —    |       | $V_{DS} = 10V$              |
| $C_{rss}$    | Reverse Transfer Capacitance    | —    | 150  | —    |       | $f = 1.0MHz$                |

## Avalanche Characteristics

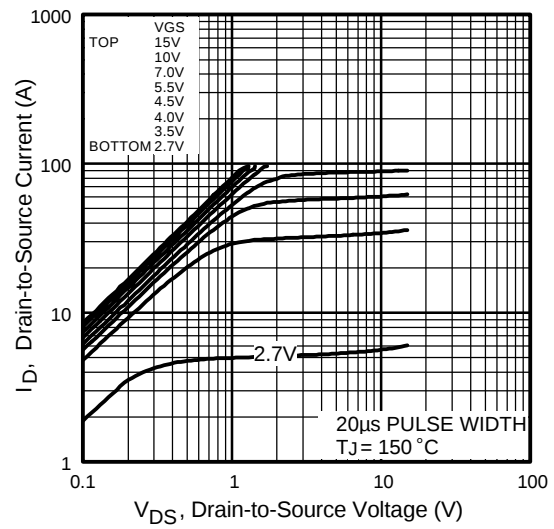
| Symbol   | Parameter                      | Typ. | Max. | Units |
|----------|--------------------------------|------|------|-------|
| $E_{AS}$ | Single Pulse Avalanche Energy② | —    | 240  | mJ    |
| $I_{AR}$ | Avalanche Current①             | —    | 9.6  | A     |

## Diode Characteristics

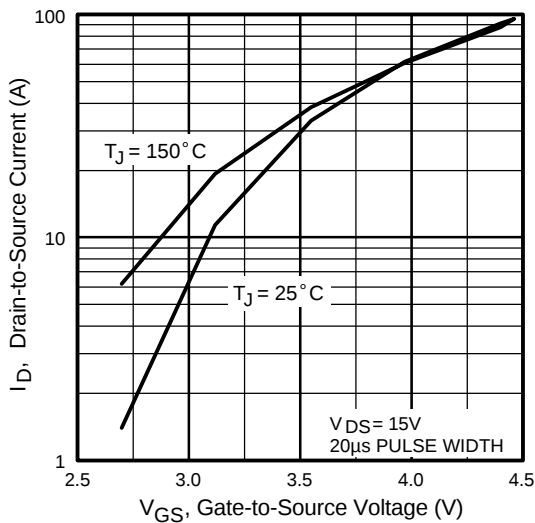
| Symbol   | Parameter                              | Min. | Typ. | Max. | Units | Conditions                                                                                                                                           |
|----------|----------------------------------------|------|------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —    | —    | 2.3  | A     | MOSFET symbol showing the integral reverse p-n junction diode.  |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ①   | —    | —    | 100  |       |                                                                                                                                                      |
| $V_{SD}$ | Diode Forward Voltage                  | —    | 0.8  | 1.3  | V     | $T_J = 25^\circ\text{C}, I_S = 9.6A, V_{GS} = 0V$ ④                                                                                                  |
|          |                                        | —    | 0.66 | —    |       | $T_J = 125^\circ\text{C}, I_S = 9.6A, V_{GS} = 0V$ ④                                                                                                 |
| $t_{rr}$ | Reverse Recovery Time                  | —    | 44   | 66   | ns    | $T_J = 25^\circ\text{C}, I_F = 9.6A, V_R = 10V$                                                                                                      |
| $Q_{rr}$ | Reverse Recovery Charge                | —    | 60   | 90   | nC    | $di/dt = 100A/\mu s$ ④                                                                                                                               |
| $t_{rr}$ | Reverse Recovery Time                  | —    | 44   | 66   | ns    | $T_J = 125^\circ\text{C}, I_F = 9.6A, V_R = 10V$                                                                                                     |
| $Q_{rr}$ | Reverse Recovery Charge                | —    | 64   | 96   | nC    | $di/dt = 100A/\mu s$ ④                                                                                                                               |



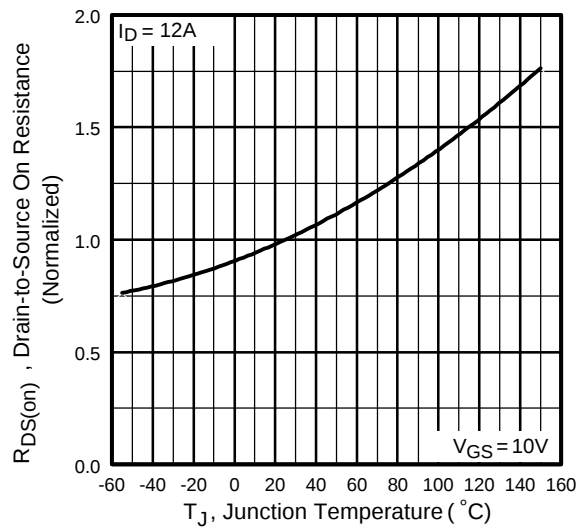
**Fig 1.** Typical Output Characteristics



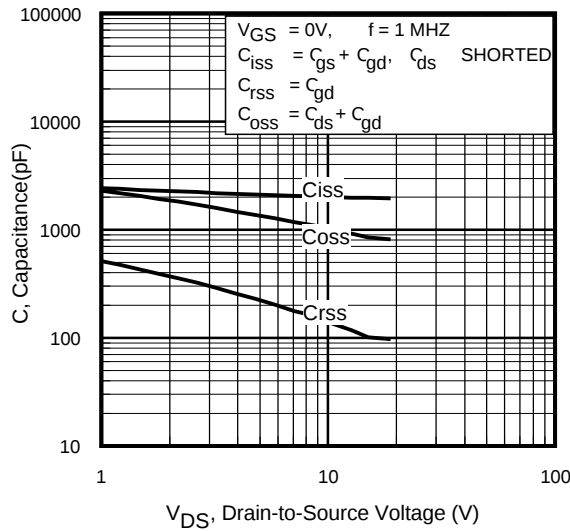
**Fig 2.** Typical Output Characteristics



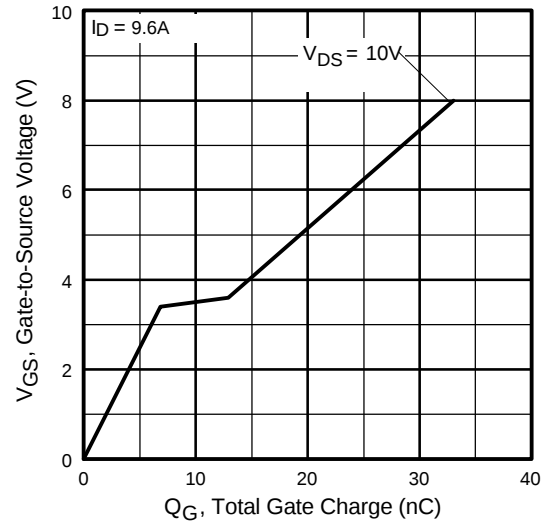
**Fig 3.** Typical Transfer Characteristics



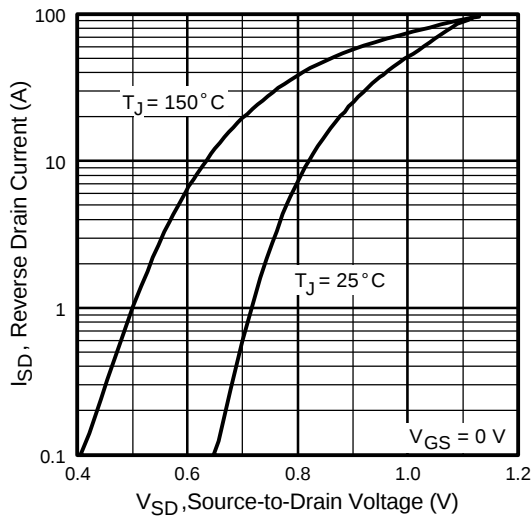
**Fig 4.** Normalized On-Resistance  
Vs. Temperature



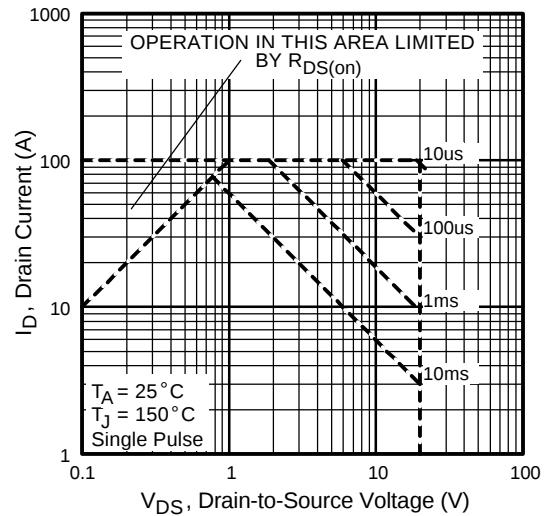
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage

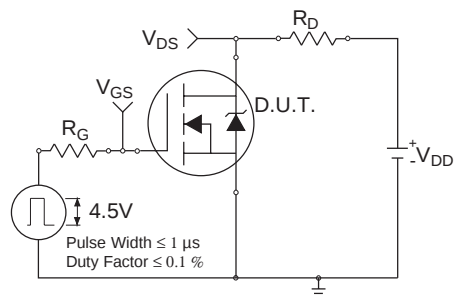
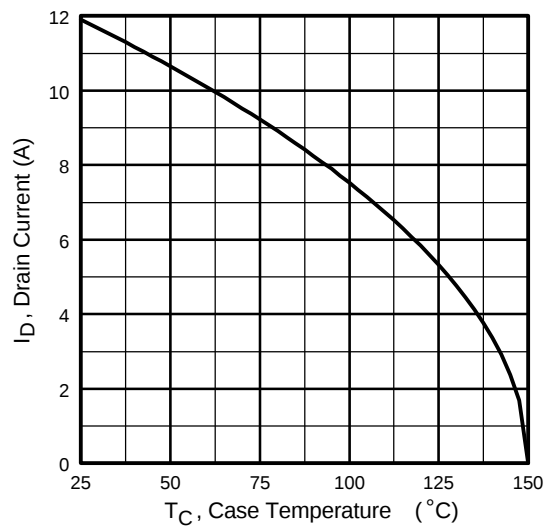


**Fig 8.** Maximum Safe Operating Area

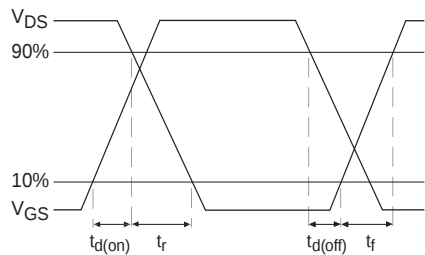
**Fig 6.** On-Resistance Vs. Drain Current

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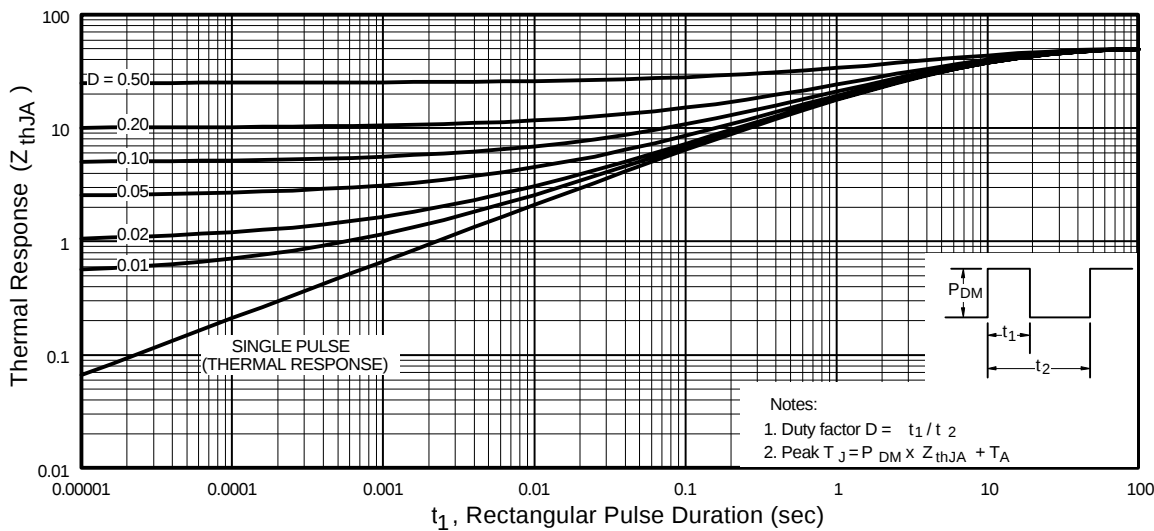
**IRF7460**



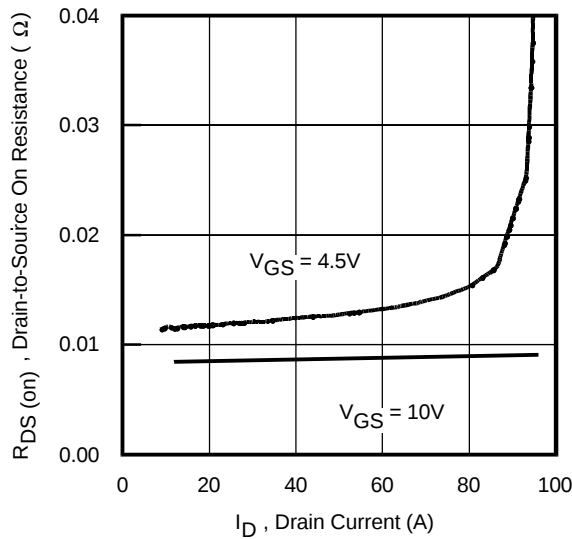
**Fig 10a.** Switching Time Test Circuit



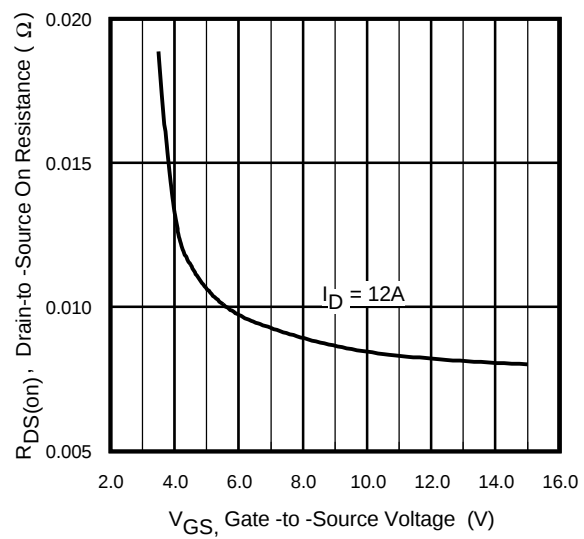
**Fig 10b.** Switching Time Waveforms



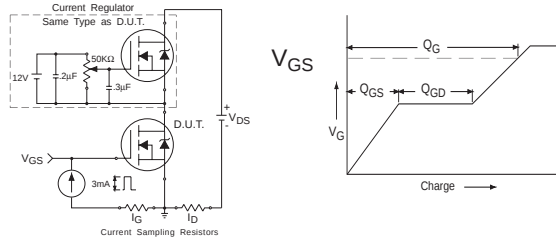
**Fig 10.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



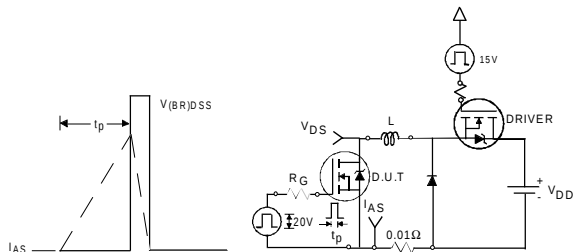
**Fig 12.** On-Resistance Vs. Drain Current



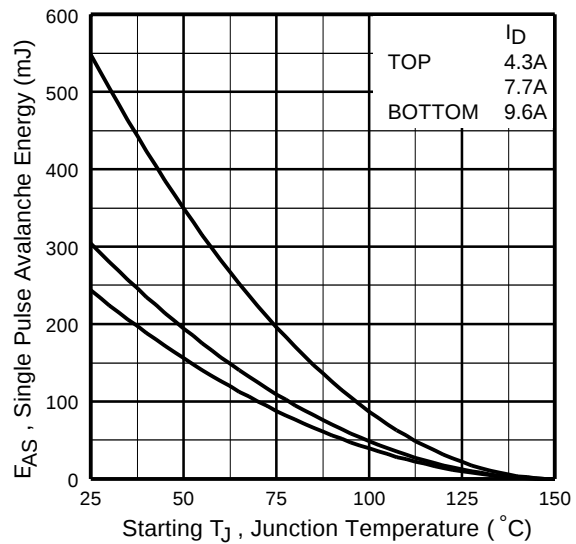
**Fig 13.** On-Resistance Vs. Gate Voltage



**Fig 13a&b.** Basic Gate Charge Test Circuit and Waveform

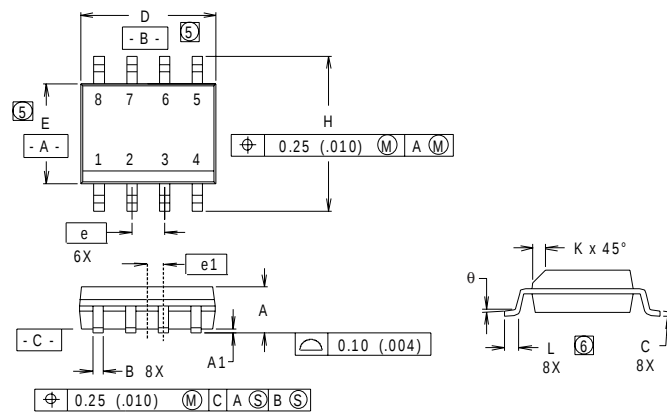


**Fig 14a&b.** Unclamped Inductive Test circuit and Waveforms



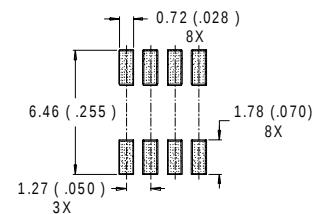
**Fig 14c.** Maximum Avalanche Energy Vs. Drain Current

## SO-8 Package Details



| DIM | INCHES     |       | MILLIMETERS |      |
|-----|------------|-------|-------------|------|
|     | MIN        | MAX   | MIN         | MAX  |
| A   | .0532      | .0688 | 1.35        | 1.75 |
| A1  | .0040      | .0098 | 0.10        | 0.25 |
| B   | .014       | .018  | 0.36        | 0.46 |
| C   | .0075      | .0098 | 0.19        | 0.25 |
| D   | .189       | .196  | 4.80        | 4.98 |
| E   | .150       | .157  | 3.81        | 3.99 |
| e   | .050 BASIC |       | 1.27 BASIC  |      |
| e1  | .025 BASIC |       | 0.635 BASIC |      |
| H   | .2284      | .2440 | 5.80        | 6.20 |
| K   | .011       | .019  | 0.28        | 0.48 |
| L   | 0.16       | .050  | 0.41        | 1.27 |
| θ   | 0°         | 8°    | 0°          | 8°   |

RECOMMENDED FOOTPRINT

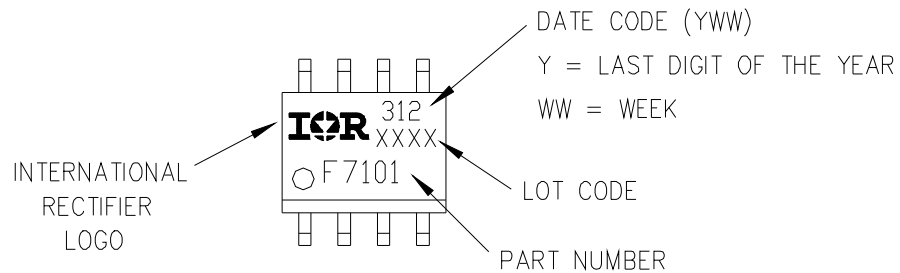


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS  
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (0.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

## SO-8 Part Marking

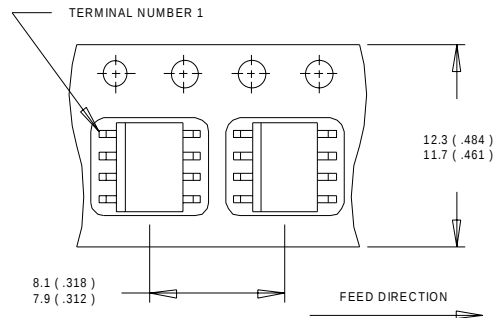
EXAMPLE: THIS IS AN IRF7101



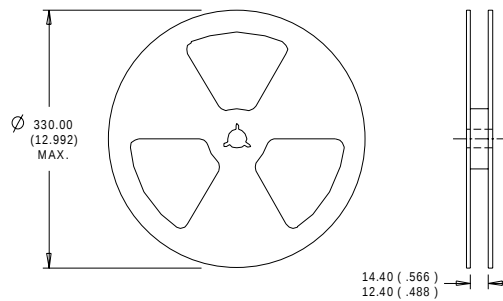
# IRF7460

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## SO-8 Tape and Reel



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 5.2\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 9.6\text{A}$ .
- ③ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ④ When mounted on 1 inch square copper board,  $t < 10\text{ sec}$

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Industrial market.  
Qualification Standards can be found on IR's Web site.

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**IR** Rectifier

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